

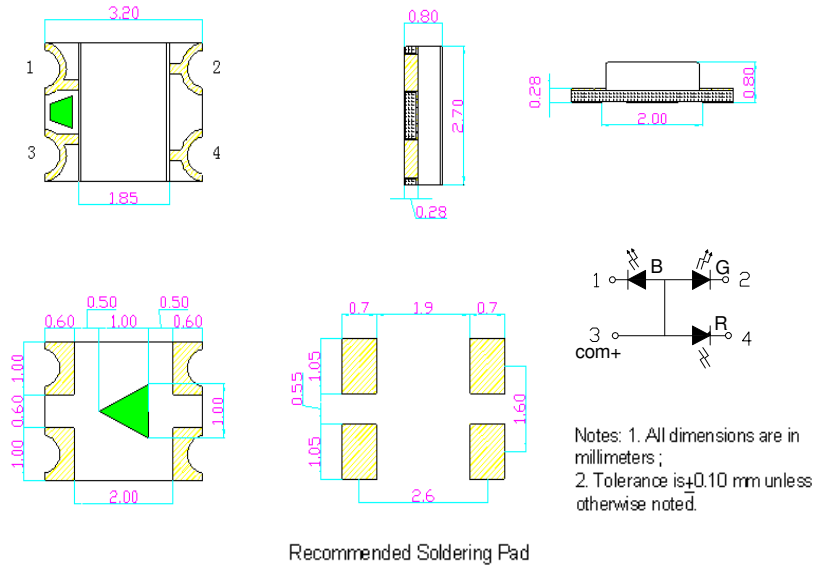
■Features

- Full-Color
- Super high brightness of reverse mount LED
- Water Clear Flat Mold
- Compact package outline
(LxWxT) of 3.2mm x 2.7mm x 0.8mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension



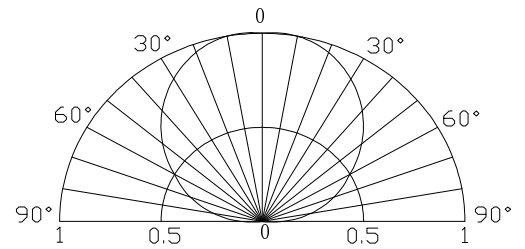
■Absolute Maximum Rating

($T_a=25^\circ\text{C}$)

Item	Symbo	Value		Unit
		R	G/B	
DC Forward Current	I_F	30	30	mA
Pulse Forward Current*	I_{FP}	70	100	mA
Reverse Voltage	V_R	5	5	V
Power Dissipation	P_D	78	108	mW
Operating Temperature	T_{opr}	-25 ~ +85		$^\circ\text{C}$
Storage Temperature	T_{stg}	-35 ~ +85		$^\circ\text{C}$
Lead Soldering Temperature	T_{sol}	260 $^\circ\text{C}$ /5sec		-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

($T_a=25^\circ\text{C}$)

Part Number	Color		V_F (V)			I_R (μA)	I_v (mcd)			λ_D (nm)			2 θ 1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			$I_F=20\text{mA}$			$V_R=5\text{V}$	$I_F=20\text{mA}$						
OSTB1209C1N-A	Blue	B	2.8	3.1	3.6	10	-	150	-	465	470	475	120
	Pure Green	G	2.8	3.1	3.6	10	-	500	-	520	525	530	120
	Red	R	1.8	2.1	2.6	10	-	250	-	620	625	630	120

* 1 Tolerance of measurements of dominant wavelength is $\pm 1\text{nm}$

* 2 Tolerance of measurements of luminous intensity is $\pm 15\%$

* 3 Tolerance of measurements of forward voltage is $\pm 0.1\text{V}$

■ **Cautions:**

1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
2. Heat generation must be taken into design consideration when using the LED.
3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C.
(The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.